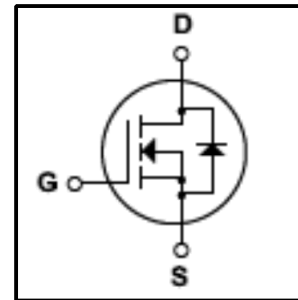


Silicon N-Channel MOSFET

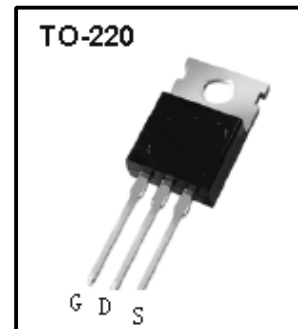
Features

- 12A,650V, $R_{DS(on)}$ (Max0.78 Ω)@ $V_{GS}=10V$
- Ultra-low Gate Charge(Typical 30nC)
- Fast Switching Capability
- 100% Avalanche Tested
- Maximum Junction Temperature Range(150°C)



General Description

This Power MOSFET is produced using Winsemi's advanced planar stripe, VDMOS technology. This latest technology has been especially designed to minimize on-state resistance, have a high rugged avalanche characteristics. This devices is specially well suited for AC-DC switching power supplies, DC-DC power converters, high voltage H-bridge motor drive PMW



Absolute Maximum Ratings

| Symbol | Parameter | Value | Units |
|----------------|--|----------|---------------|
| V_{DSS} | Drain Source Voltage | 650 | V |
| I_D | Continuous Drain Current(@ $T_c=25^\circ C$) | 12 | A |
| | Continuous Drain Current(@ $T_c=100^\circ C$) | | A |
| I_{DM} | Drain Current Pulsed (Note1) | | A |
| V_{GS} | Gate to Source Voltage | ± 30 | V |
| E_{AS} | Single Pulsed Avalanche Energy (Note 2) | 990 | mJ |
| E_{AR} | Repetitive Avalanche Energy (Note 1) | 22 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3) | 4.5 | V/ns |
| P_D | Total Power Dissipation(@ $T_c=25^\circ C$) | 178 | W |
| | Derating Factor above $25^\circ C$ | 1.43 | W/ $^\circ C$ |
| T_J, T_{stg} | Junction and Storage Temperature | -55~150 | $^\circ C$ |
| T_L | Channel Temperature | 300 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Value | | | Units |
|-----------|---|-------|-----|------|------------|
| | | Min | Typ | Max | |
| R_{QJC} | Thermal Resistance, Junction-to-Case | - | - | 0.70 | $^\circ C$ |
| R_{QCS} | Thermal Resistance, Case-to-Sink | - | - | - | $^\circ C$ |
| R_{QJA} | Thermal Resistance, Junction-to-Ambient | - | - | 62.5 | W |

Electrical Characteristics (Tc = 25°C)

| Characteristics | | Symbol | Test Condition | Min | Type | Max | Unit |
|---|---------------|---------------|---|----------|------|-----------|---------------|
| Gate leakage current | | I_{GSS} | $V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$ | - | - | ± 100 | nA |
| Gate-source breakdown voltage | | $V_{(BR)GSS}$ | $I_G = \pm 10\ \mu\text{A}, V_{DS} = 0\text{ V}$ | ± 30 | - | - | V |
| Drain cut-off current | | I_{DSS} | $V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$ | - | - | 10 | μA |
| | | | $V_{DS} = 480\text{ V}, T_c = 125^\circ\text{C}$ | - | - | 100 | μA |
| Drain-source breakdown voltage | | $V_{(BR)DSS}$ | $I_D = 250\ \mu\text{A}, V_{GS} = 0\text{ V}$ | 650 | - | - | V |
| Gate threshold voltage | | $V_{GS(th)}$ | $V_{DS} = 10\text{ V}, I_D = 250\ \mu\text{A}$ | 3 | - | 4.5 | V |
| Drain-source ON resistance | | $R_{DS(ON)}$ | $V_{GS} = 10\text{ V}, I_D = 6\text{ A}$ | - | 0.64 | 0.78 | Ω |
| Forward Transconductance | | gfs | $V_{DS} = 50\text{ V}, I_D = 6\text{ A}$ | - | 6.4 | - | S |
| Input capacitance | | C_{iss} | $V_{DS} = 25\text{ V},$ $V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$ | - | 1830 | - | pF |
| Reverse transfer capacitance | | C_{rss} | | - | 155 | - | |
| Output capacitance | | C_{oss} | | - | 2.0 | - | |
| Switching time | Rise time | tr | $V_{DD} = 325\text{ V},$ $I_D = 12\text{ A}$ $R_G = 25\ \Omega$ (Note4,5) | - | 50 | - | ns |
| | Turn-on time | ton | | - | 49 | - | |
| | Fall time | tf | | - | 310 | - | |
| | Turn-off time | toff | | - | 54 | - | |
| Total gate charge (gate-source plus gate-drain) | | Q_g | $V_{DD} = 520\text{ V},$ $V_{GS} = 10\text{ V},$ $I_D = 12\text{ A}$ (Note4,5) | - | 51.7 | - | nC |
| Gate-source charge | | Q_{gs} | | - | 9.6 | - | |
| Gate-drain ("miller") Charge | | Q_{gd} | | - | 18.6 | - | |

Source-Drain Ratings and Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Type | Max | Unit |
|----------------------------------|-----------|---|-----|------|-----|---------------|
| Continuous drain reverse current | I_{DR} | - | - | - | 12 | A |
| Pulse drain reverse current | I_{DRP} | - | - | - | 48 | A |
| Forward voltage (diode) | V_{DSF} | $I_{DR} = 10\text{ A}, V_{GS} = 0\text{ V}$ | - | - | 1.4 | V |
| Reverse recovery time | trr | $I_{DR} = 10\text{ A}, V_{GS} = 0\text{ V},$ $dI_{DR} / dt = 100\text{ A} / \mu\text{s}$ | - | 450 | - | ns |
| Reverse recovery charge | Qrr | | - | 5.0 | - | μC |

- Note 1.Repeativity rating :pulse width limited by junction temperature
 2.L=14mH,I_{AS}=12A,V_{DD}=95V,R_G=25Ω,Starting T_J=25°C
 3.I_{SD}≤10A,dI/dt≤200A/μs, V_{DD}<BV_{DSS},STARTING T_J=25°C
 4.Pulse Test: Pulse Width≤300us,Duty Cycle≤2%
 5.Essentially independent of operating temperature.

This transistor is an electrostatic sensitive device

Please handle with caution

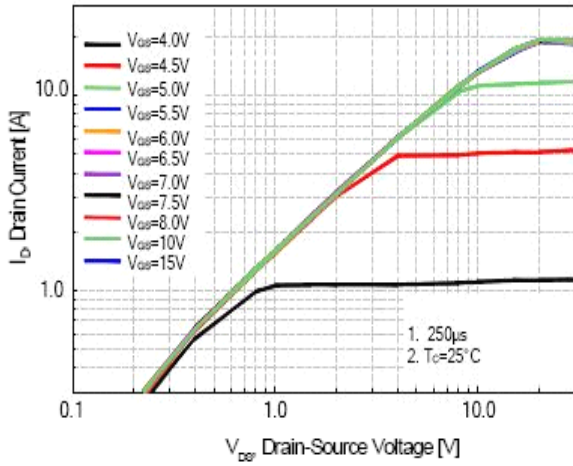


Fig. 1 On-State Characteristics

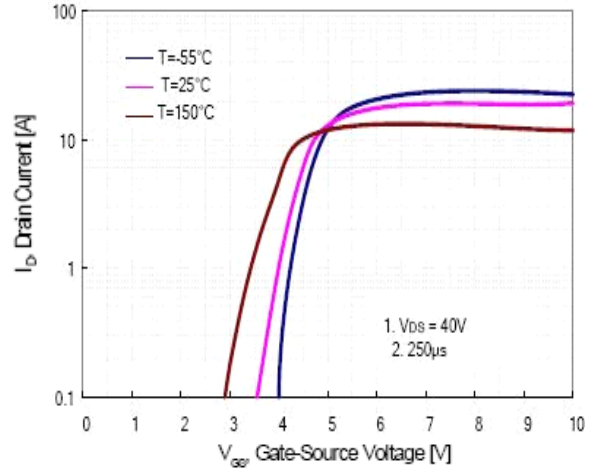


Fig.2 Transfer Current Characteristics

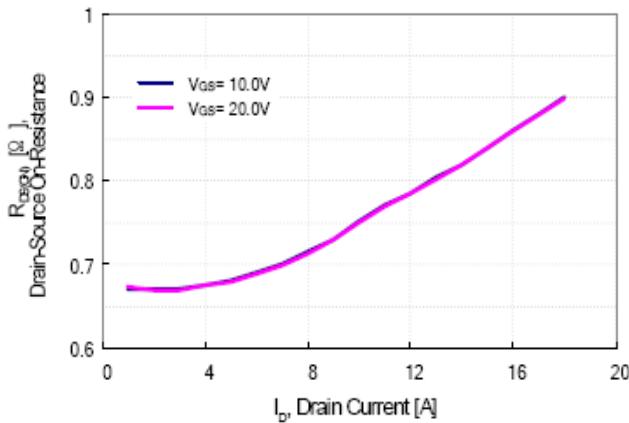


Fig.3 On-Resistance Variation vs Drain Current

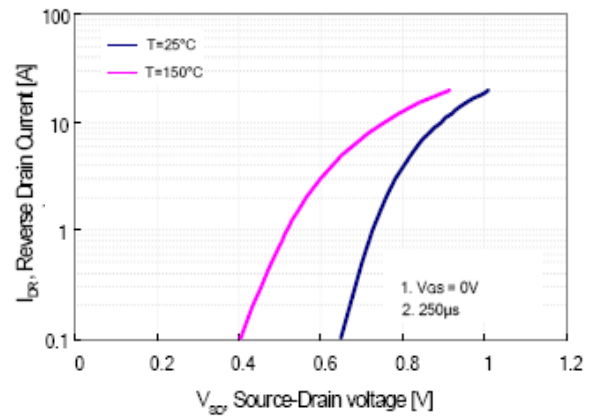


Fig.4 Body Diode Forward Voltage Variation with Source Current And Temperature

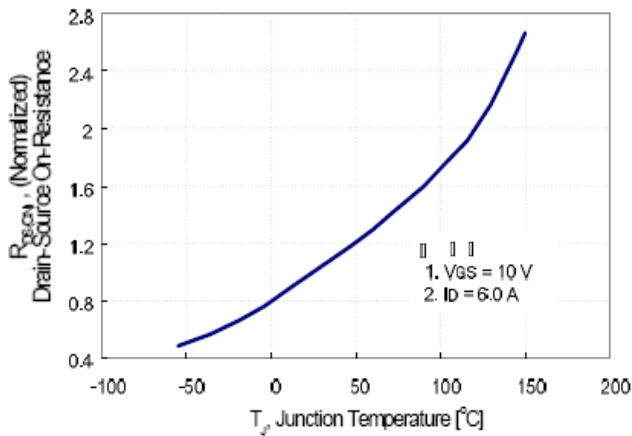


Fig.5 On-Resistance Variation vs Junction Temperature

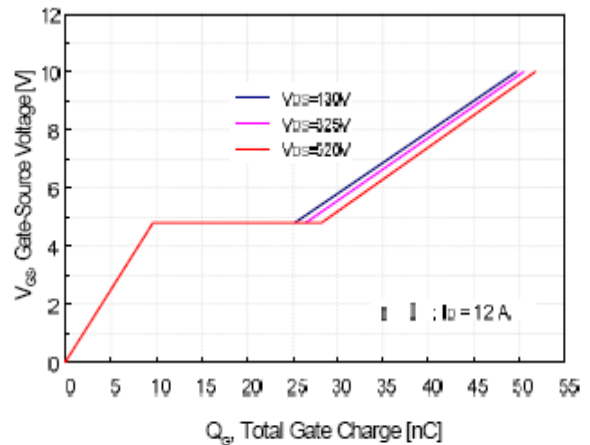


Fig.6 Gate Charge Characteristics

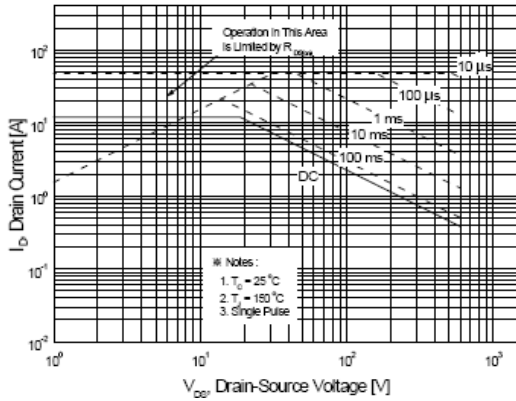


Fig.7 Maximum Safe Operation Area

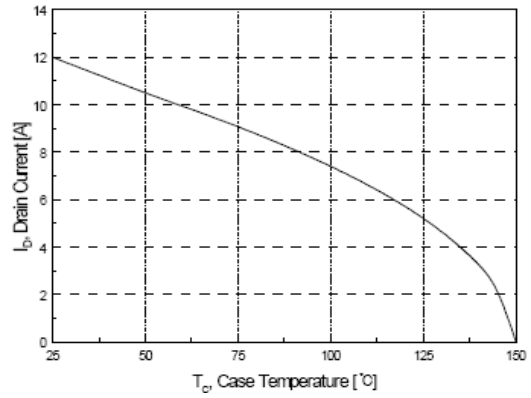


Fig.8 Maximum Drain Current vs Case Temperature

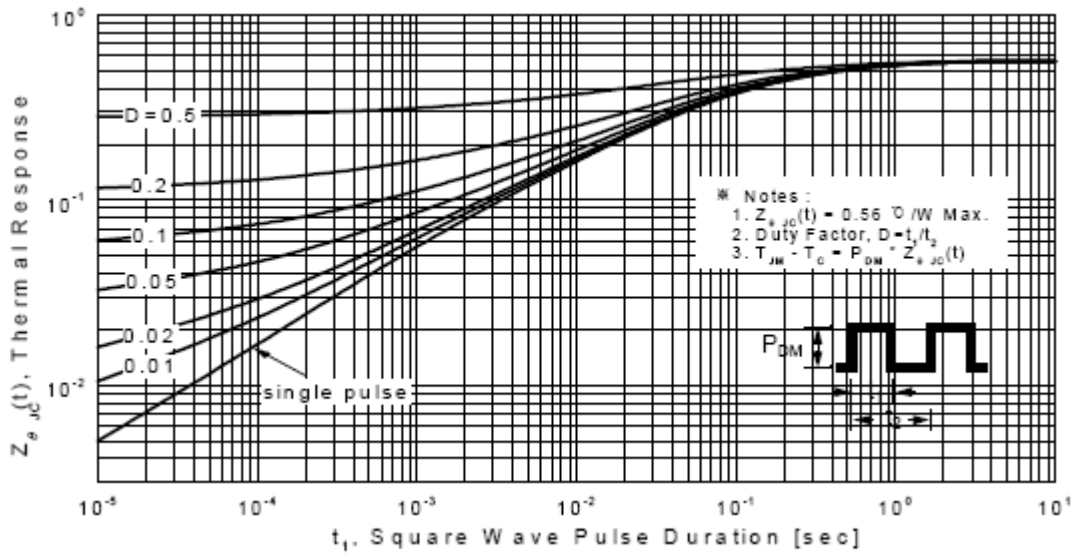


Fig.9 Transient Thermal Response Curve

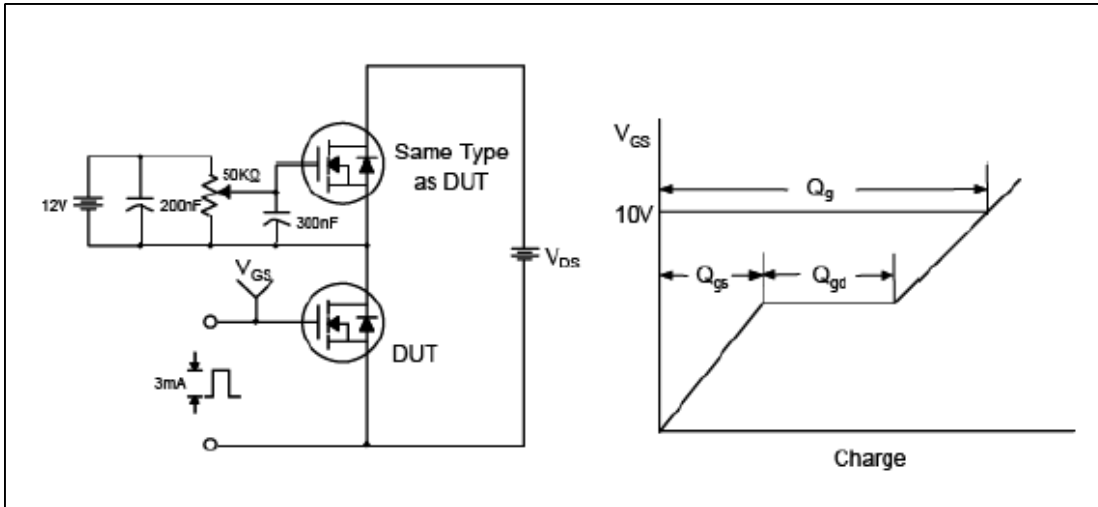


Fig.10 Gate Test circuit & Waveform

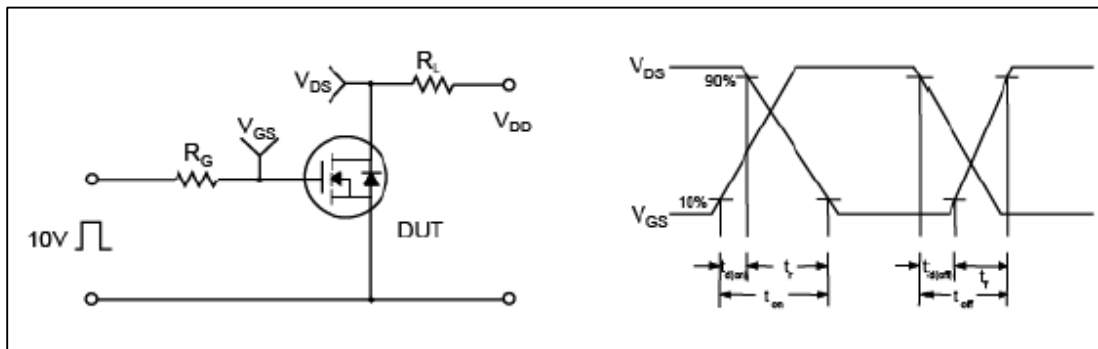


Fig.11 Resistive Switching Test Circuit & Waveform

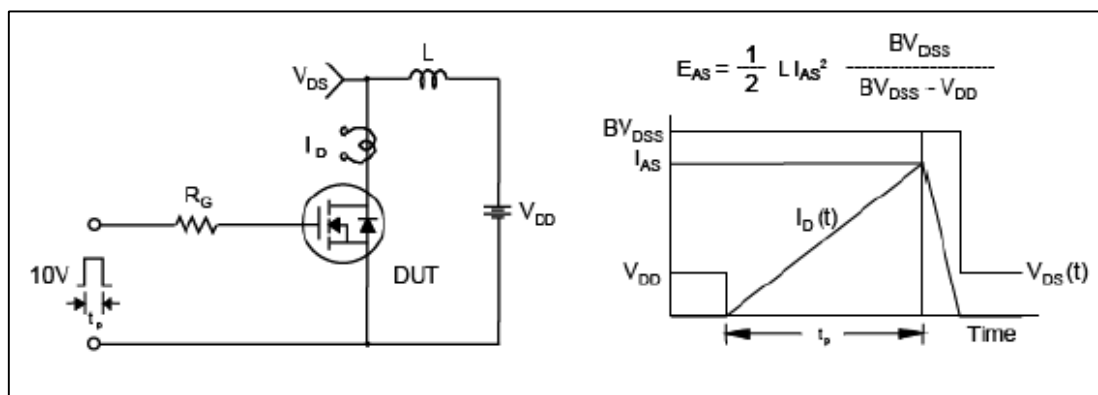


Fig.12 Uncamped Inductive Switching Test Circuit & Waveform

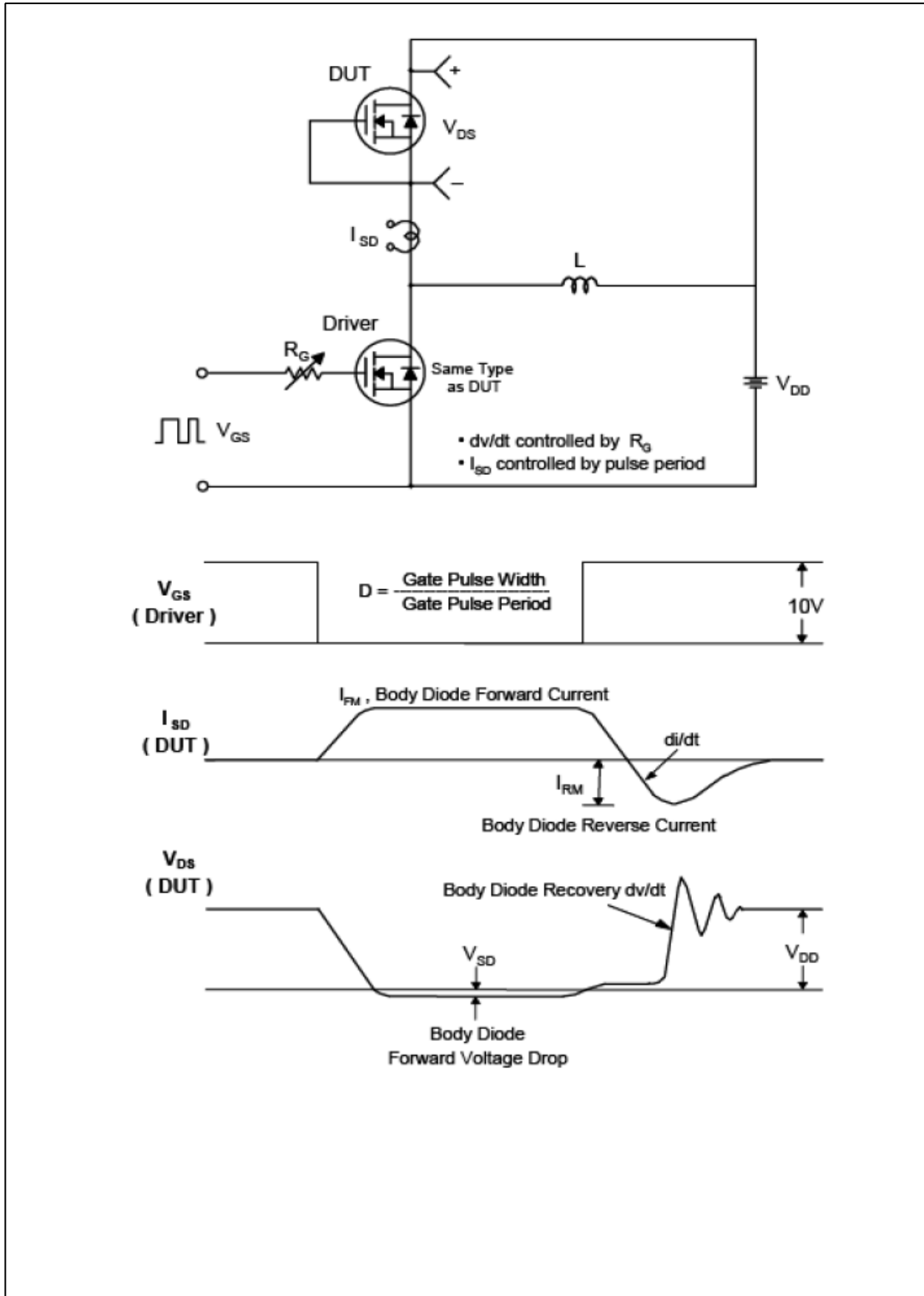


Fig.13 Peak Diode Recovery dv/dt Test Circuit & Waveform

TO-220 Package Dimension

